


NOTES

- MATERIALS:**
LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.
- FINISH:**
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 200 TO 300 MICRONS (2.5um-7.6um) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICRONS (1um-2um) THICK).
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
- PACKAGE MISMATCH:** BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.
- UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.**
- PACKAGE CONFORMS TO JEDEC MO-220**

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		UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS TOLERANCES ARE:		DRAWN	D. Abbe	10/3/11	 TITLE: QP-QFN40-5MM-0.40MM
		ANGULAR: ±0.5 degree .X = ±0.76 .XX: ±0.25 .XXX = ±0.13 .XXXX = ±0.01		CHECKED	S. Swen	10/3/11	
				ENG APPR.	S. Swen	10/3/11	
		MATERIAL		COMMENTS:			
		FINISH					
NEXT ASSY	USED ON	SEE NOTE 1					
APPLICATION		DO NOT SCALE DRAWING					
SIZE	DWG. NO.	REV					
B	500479	A					
SCALE: 12:1	WEIGHT:	SHEET 1 OF 1					

